

Abstract of the Disclosure

In holes formed in a multi-layer wiring board for transmitting differential signals, a first hole is formed, an insulating portion is formed by filling the first hole with an insulating resin, a pair of second holes is formed for transmitting the differential signals to the formed insulating portion, and the pair of second holes is arranged symmetrically each other with respect to a center axis of the first hole for forming a coaxial structure.